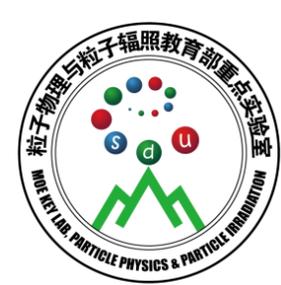




山东大学  
SHANDONG UNIVERSITY



# R&D on sensors for the silicon pixelated tracker

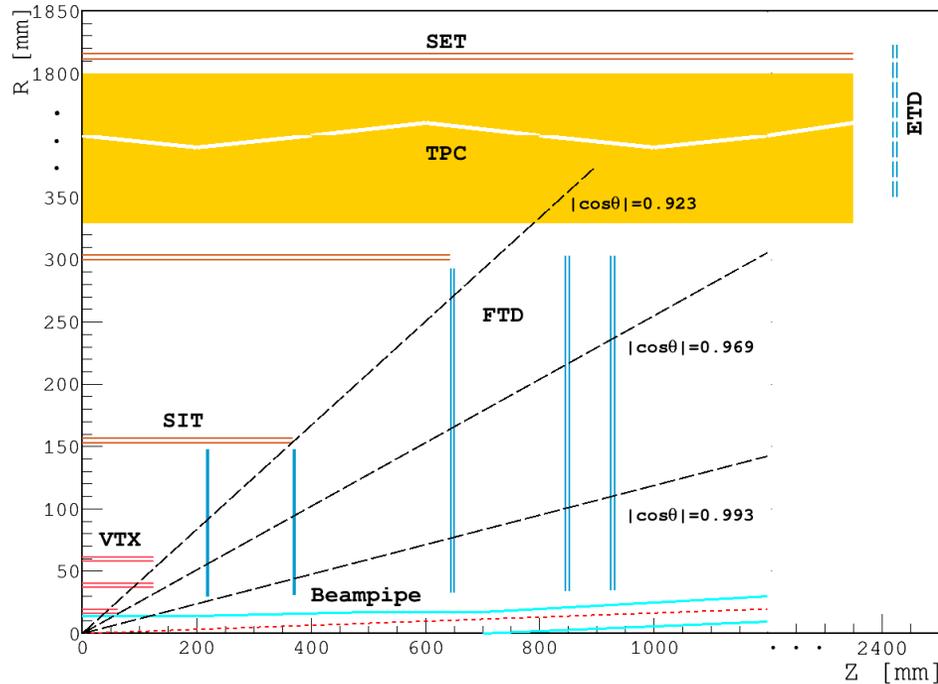
Long LI, Liang Zhang, Jianing Dong, Meng Wang

2019 International workshop on CEPC, Nov. 19<sup>th</sup>, IHEP

# Outlines

- 1. Brief introduction of CEPC silicon tracker**
- 2. Introduction of SUPIX-2, a prototype of CMOS Pixel Sensor developed at Shandong University**
- 3. TCAD simulation on sensors**
- 4. Pixel circuit design**
- 5. Electronics for test system**
- 6. Status and prospects**

# CEPC silicon tracker



## Primary requirements

- ✓ Single point resolution:  $\sigma_{SP} < 7\mu\text{m}$ ,
- ✓ Material budget:  $X_0 < 0.65\%$ ,
- ✓ Radiation hardness: 3.4MRad (TID) and  $6.2 \times 10^{12}$  1MeV  $n_{eq}/\text{cm}^2$  (NIEL) per year.

## Functionalities:

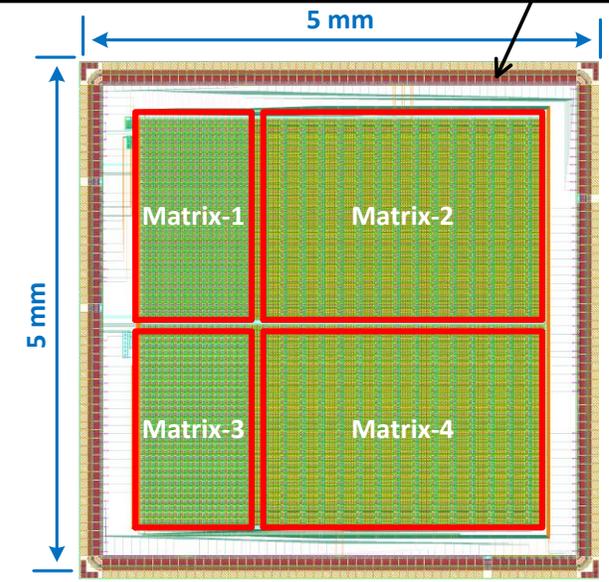
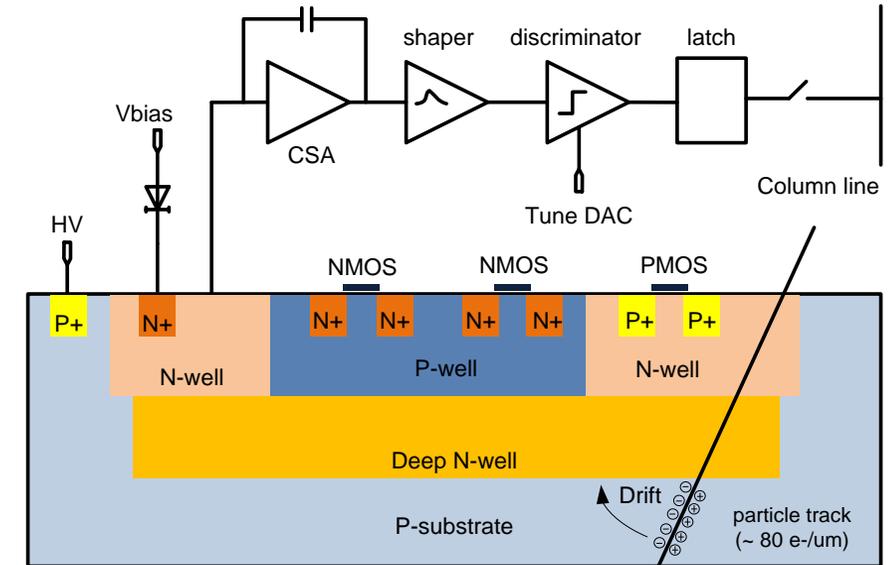
- Improving tracking efficiency and precision by high precision hit points along the trajectories,
- monitoring possible field distortion in the TPC,
- contributing detector alignment,
- separating events between bunch crossings with relative time-stamping, and
- potentially the  $dE/dx$  measurement.

# SUPIX-2 – A CMOS Pixel Sensor for CEPC

- - **SMIC 0.18  $\mu\text{m}$  technology** - -
- ✓ **Triple well: Nwell, Pwell, Deep Nwell**
- ✓ **No EPI-layer**
- ✓ **10  $\Omega\cdot\text{cm}$  substrate**
- ✓  **$d \sim \sqrt{\rho \cdot V}$**
- ✓ **SMIC 0.18  $\mu\text{m}$  process  $\rightarrow$  15 V**
- ✓ **Circuits are realized mainly by NMOS transistors**
- ✓ **PMOS is coupled with collection electrode**

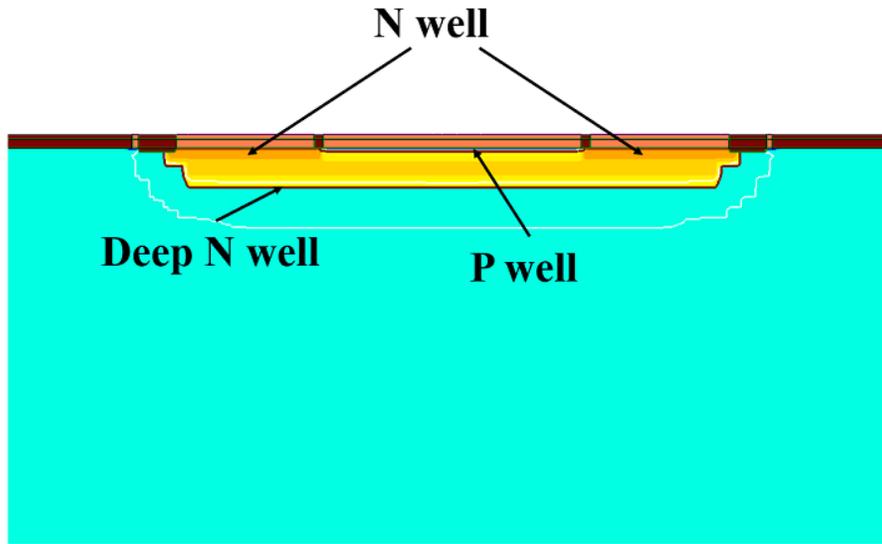
## -- Architecture of SUPIX-2 --

- ◆ **4 submatrices, each matrix is  $32 \times 16$**
- ◆ **Pixel size:  $60 \times 60 \mu\text{m}^2$ ,  $60 \times 180 \mu\text{m}^2$**
- ◆ **Rolling shutter readout mode**
- ◆ **16 parallel digital outputs**
  - **Each pixel is implemented with a charge sensitive amplifier (CSA), a shaper, a discriminator and a latch**
- ◆ **Sensitive area:  $\sim 3.84 \times 3.84 \text{ mm}^2$**

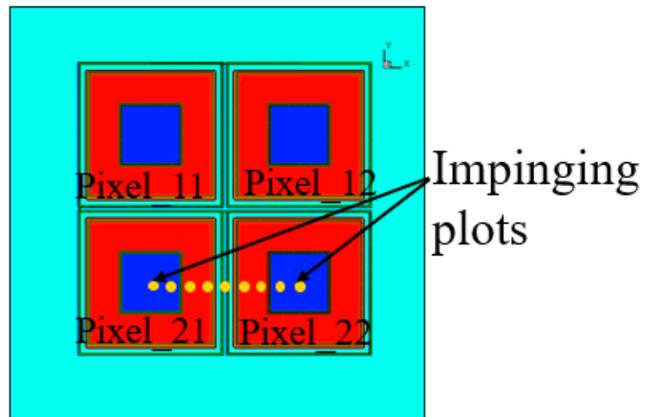


Layout of SUPIX-2

# TCAD simulation on sensor



Side view of a pixel sensor



Impinging plots along the X-axis for charge sharing simulation

**Before the circuit design, the geometry of the sensor has been optimized via TCAD.**

**Toolkit: Sentaurus SYNOPSIS Inc.**

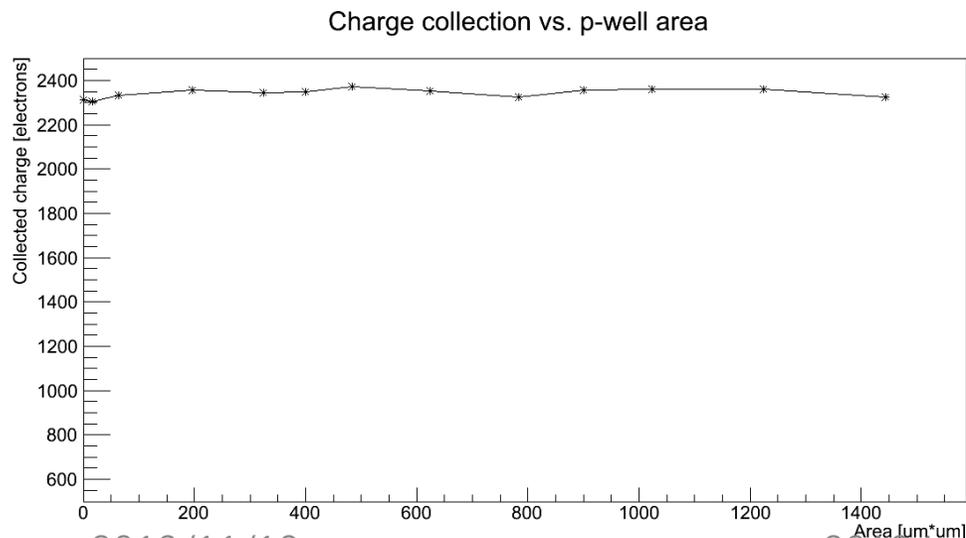
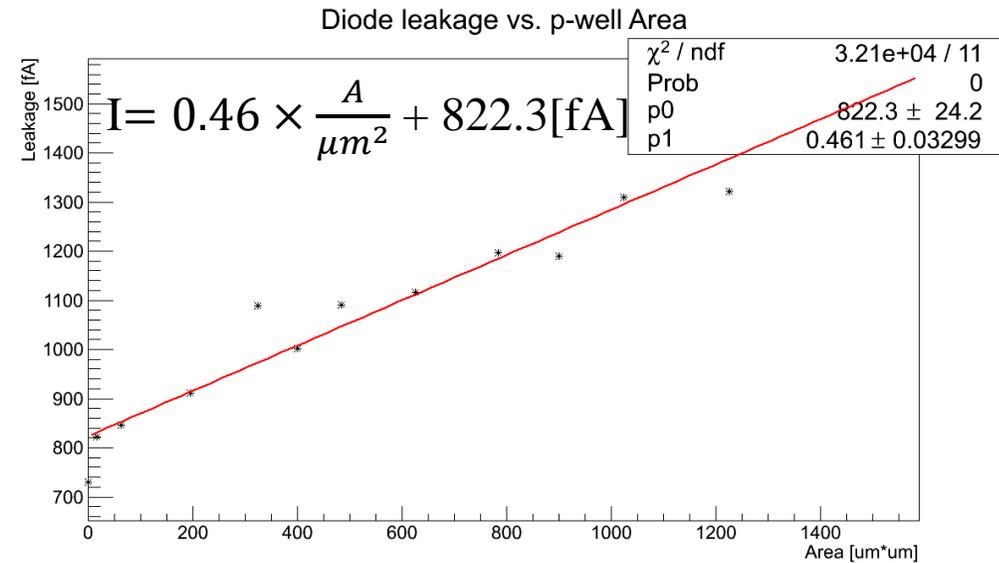
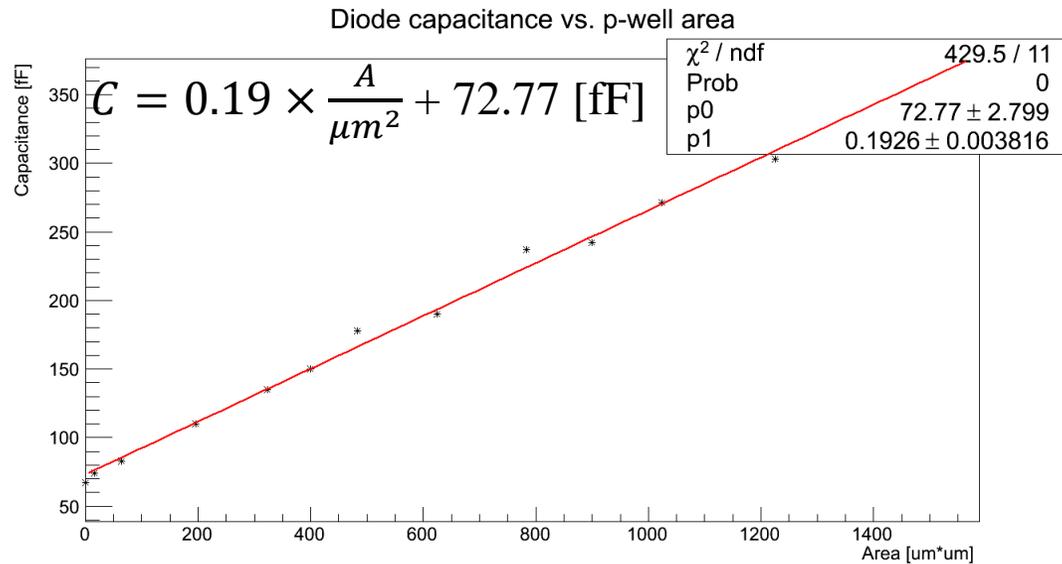
**Pixel size:  $50 \times 50 \mu m^2$  (according to the CEPC CDR)**

**Variable: Area of the p-well**

**Simulated performance:**

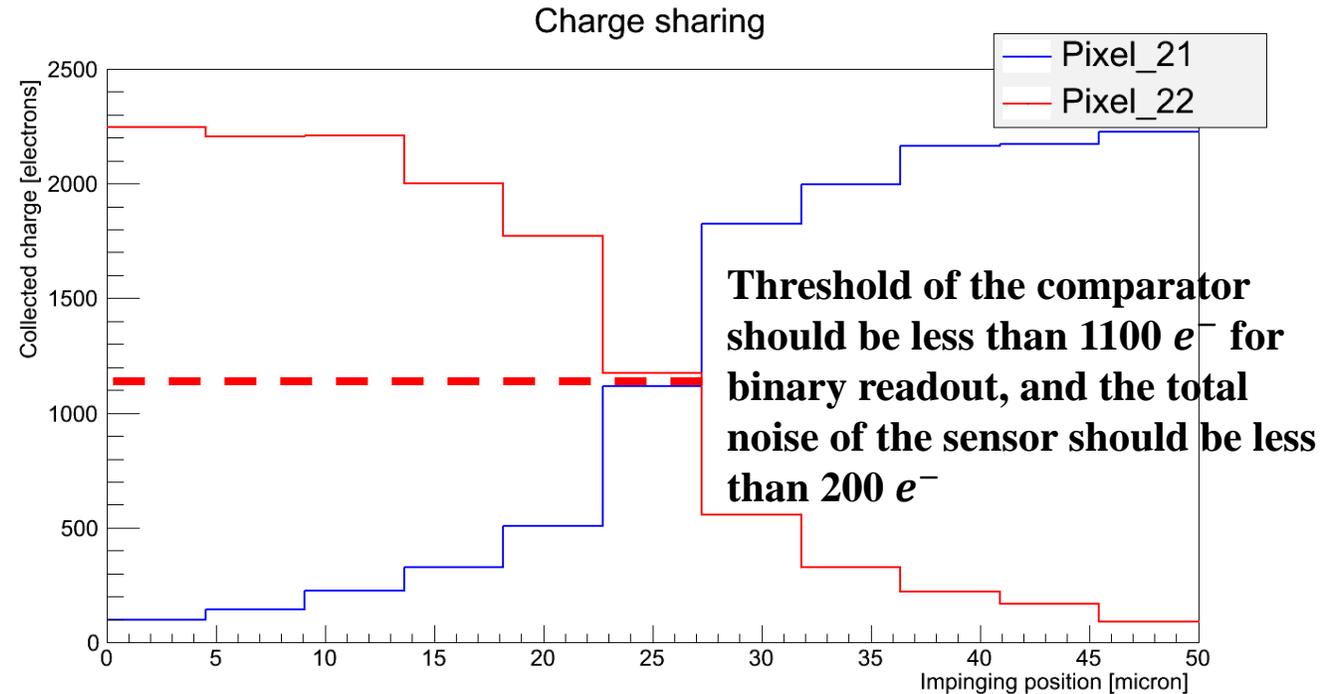
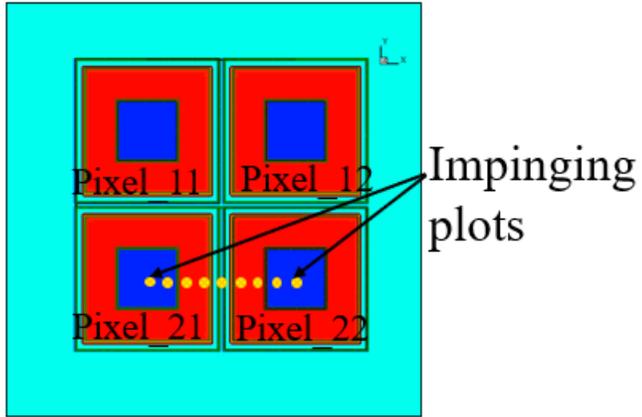
- ✓ Diode capacitance
- ✓ Diode leakage
- ✓ Charge collection (charge collecting time 100ns)
- ✓ One dimensional charge sharing
- ✓ Radiation effects (NIEL)

# Sensor performance variations caused by p-well area



The area of p-well has much effect on the diode capacitance and leakage, and roughly increase linearly against the p-well area. But it has little impact on the charge collection. In order to keep the sensor noise low, the area of the p-well should be as small as possible. For SUPIX-2,  $60 \times 60 \mu m^2$  pixel size and  $140 \mu m^2$  p-well have been chosen considering the circuit design.

# Charge sharing and radiation effects



**Sensor performance comparison before and after radiation**

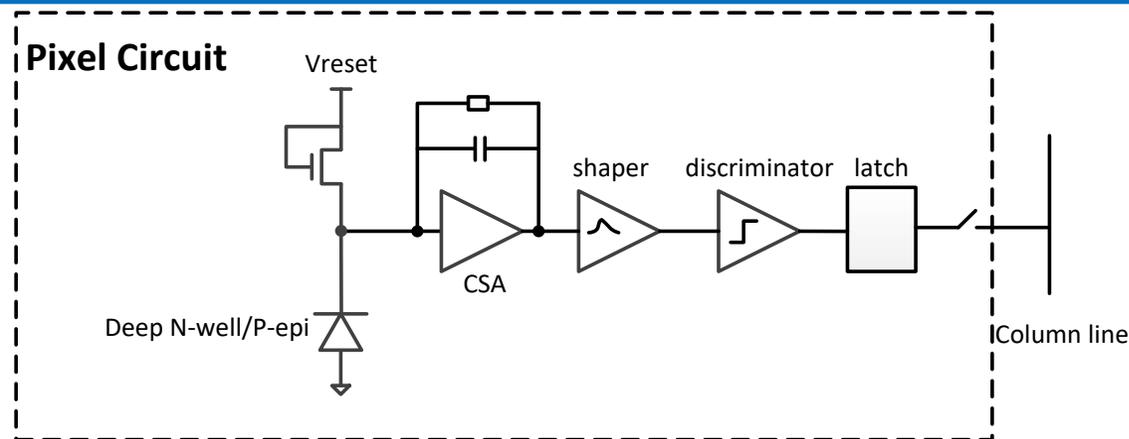
Flux(1MeV $n_{eq}/cm^2$ )	Capacitance(fF)	Leakage(fA)	Collected charge(100ns)
0	150	1002	2350 $e^-$
$6.2 \times 10^{12}$	153	2992	1780 $e^-$

The increased leakage current and lower charge collection would lead to the decrease of the SNR and lower detection efficiency after irradiation.

# Pixel circuit

## ■ Pixel circuit:

- ↪ **Charge gain (CSA + shaper):  $\sim 110 \text{ mV/ke}^-$**
- ↪ **Response time:  $\sim 2.6 \mu\text{s}$**
- ↪ **Total current:  $\sim 7.5 \mu\text{A}$**
- ↪ **The number of PMOS transistors has be kept as low as possible**
  - **CSA: single-stage cascode amplifier with 2 PMOS**
  - **Shaper: CR-RC using only NMOS transistors**
  - **Discriminator: fully differential amplifier using only NMOS**
  - **Latch: NOR gates with 4 PMOS**



# Pixel circuit

## ■ Requirements of CSA:

### ↪ Large gain of amplifier

#### ■ Improve “dynamic” input capacitance: $(A+1)C_f$

★ Gain of CSA  $\sim 1/C_f$

★ Increase charge transfer efficiency

### ↪ Small $C_f$ (feedback capacitance)

#### ■ Improve gain of CSA

★ NMOS capacitor

★ MOM (Metal-Oxide-Metal) capacitor to realize below 1fF

### ↪ Large $R_f$ (feedback resistance)

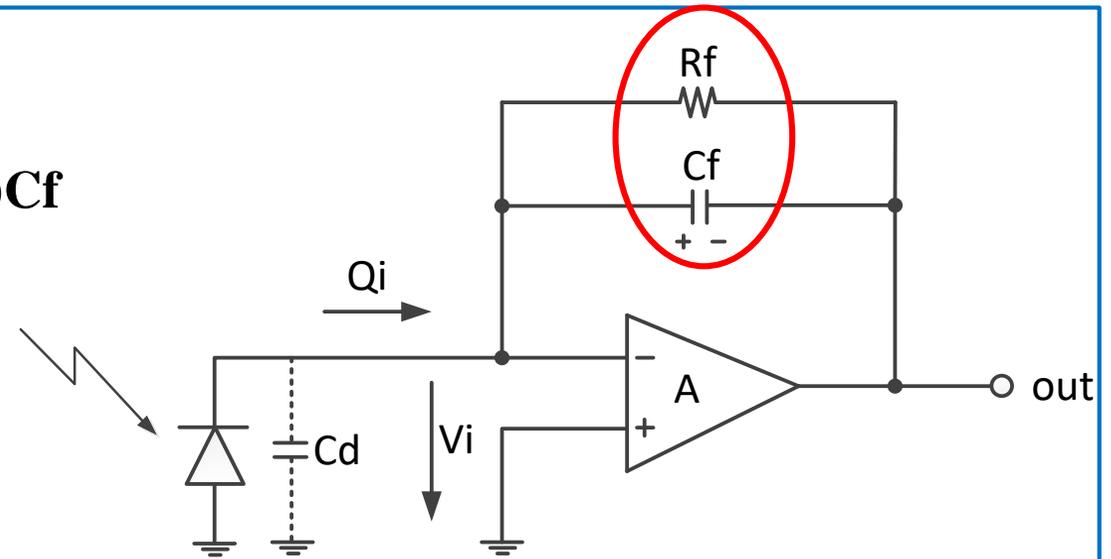
■ Amplifier needs DC feedback to discharge the input node and stabilize the operation point

■ Usually a resistor in the  $M\Omega - G\Omega$  is used

■ CMOS process don't have high value resistors

★ Use a current circuit to realize above 100  $M\Omega$

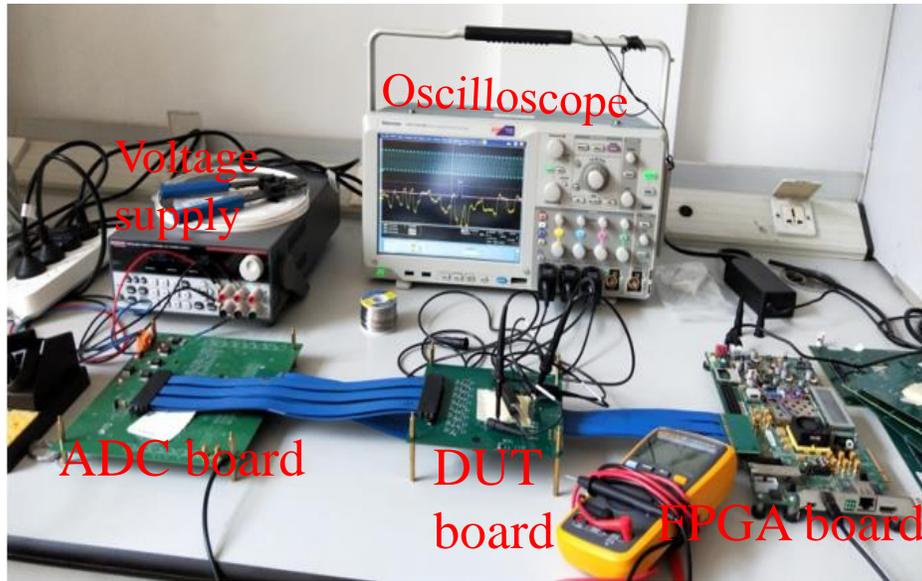
★ NMOS switch



Architecture of CSA

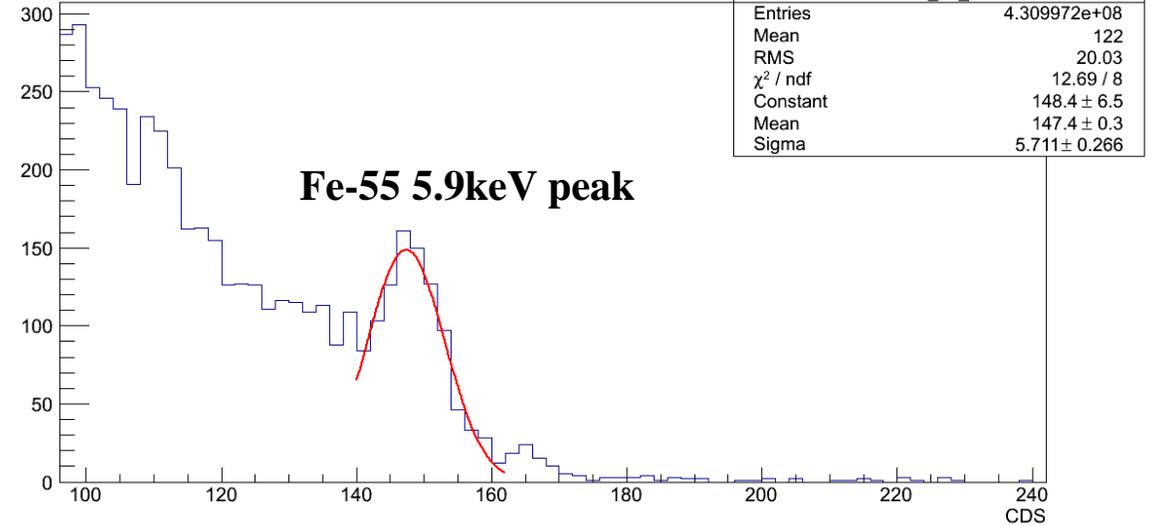
# Test system for SUPIX-1

- The test system for SUPIX-1 is running in SDU.
  - DUT board: carry the pixel sensor
  - ADC board: digitize the analog output for pixel sensor
  - FPGA evaluation board: process and transmit the data

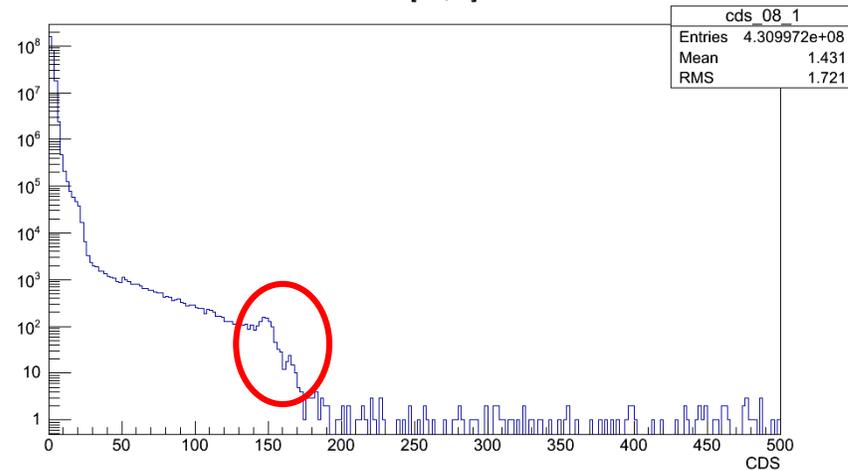


Current test system for SUPIX-1

CDS [08, 1]



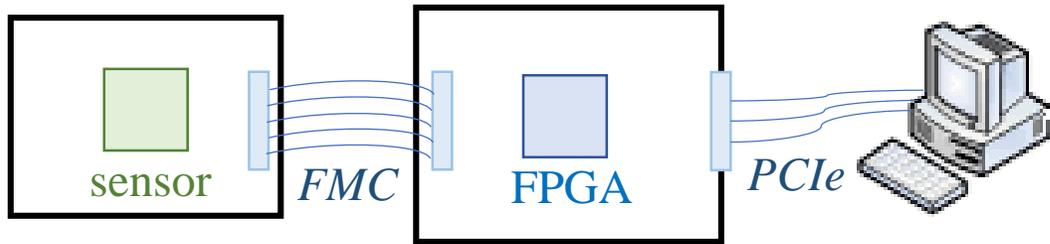
CDS [08, 1]



Radiative source test with Fe-55

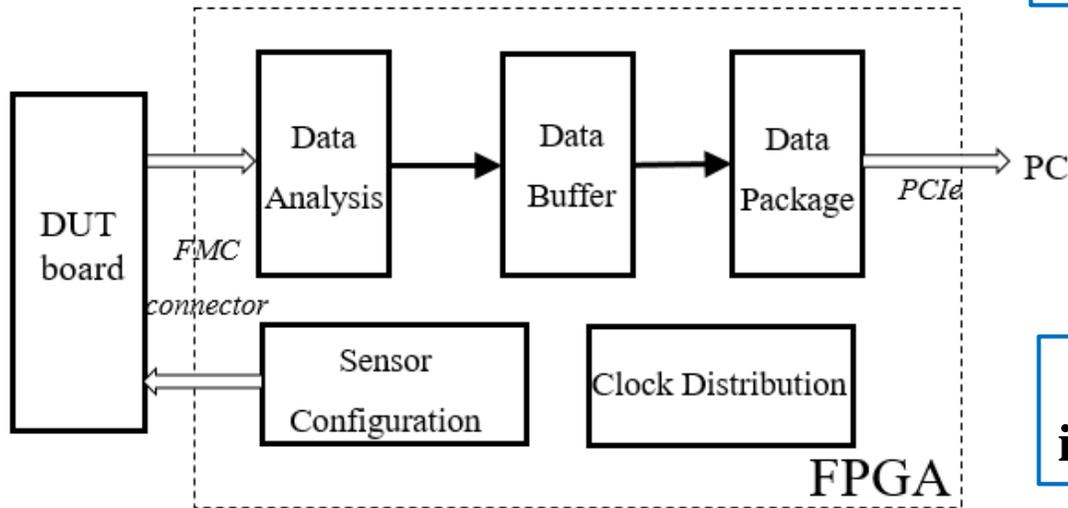
# Test system for SUPIX-2

*\*based on the SUPIX-1 test system*



SUPIX-2 test system scheme

- DUT board: carry the sensor, bias the sensor, supply the power, transfer the digital signal put out by the sensor though FMC connector and cable
- FPGA board (KC705 evaluation board): communicate with PC via PCIe, control the data loading/receiving



**Time Over Threshold method in FPGA will be realized in SUPIX-2 test system to achieve multi-bits resolution.**

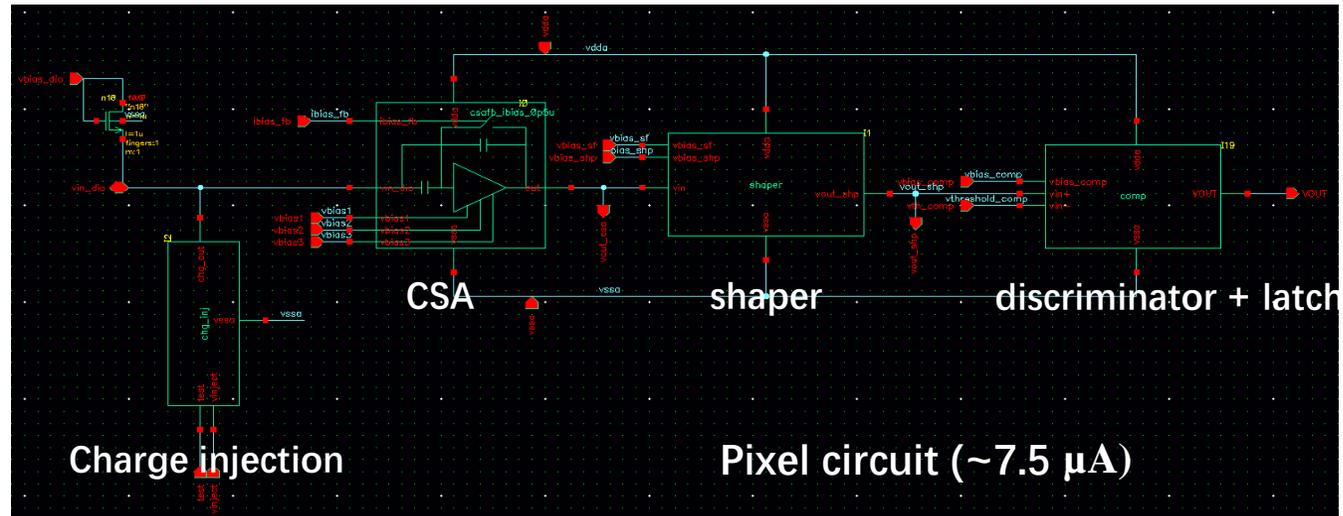
# Status and prospects

- **The technology is feasible for the tracker via the simulation, but the noise and the radiation hardness performance would be challenges. Test data is in need to verify the feasibility.**
- **Final design has been submitted on Nov. 11, and the chip is available around March 2020.**
- **Design of the test board is in progress.**

**Thanks!**

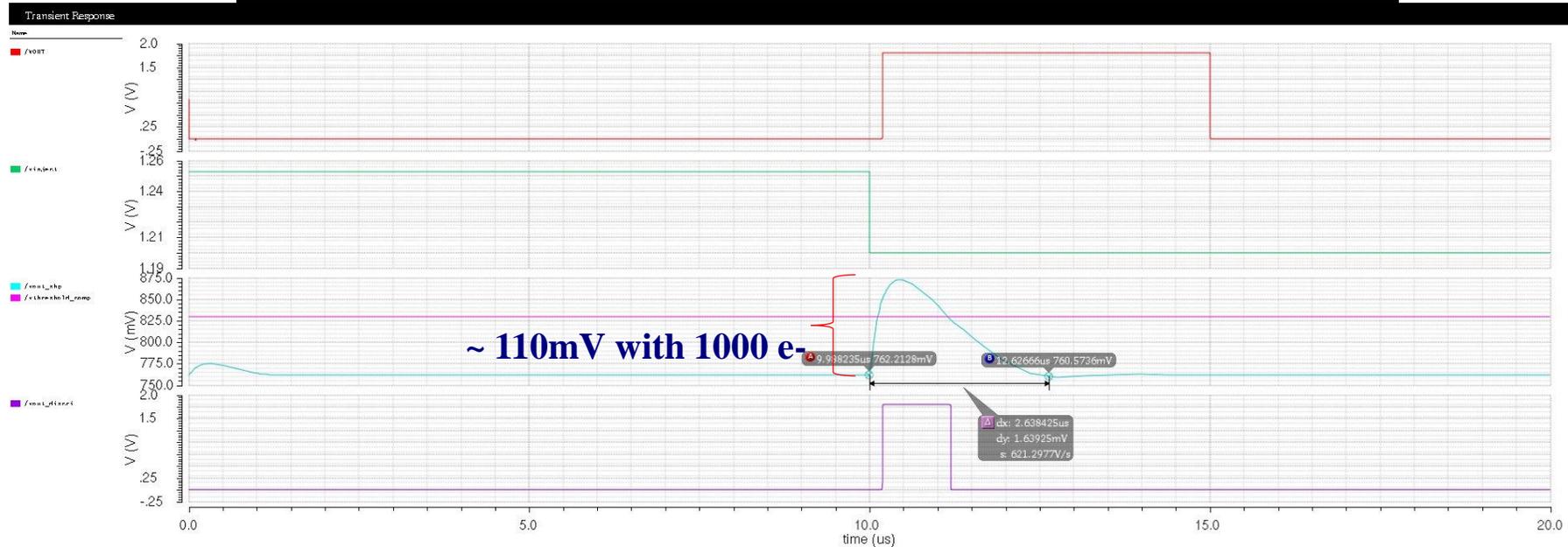
# Back up

# Pixel circuit

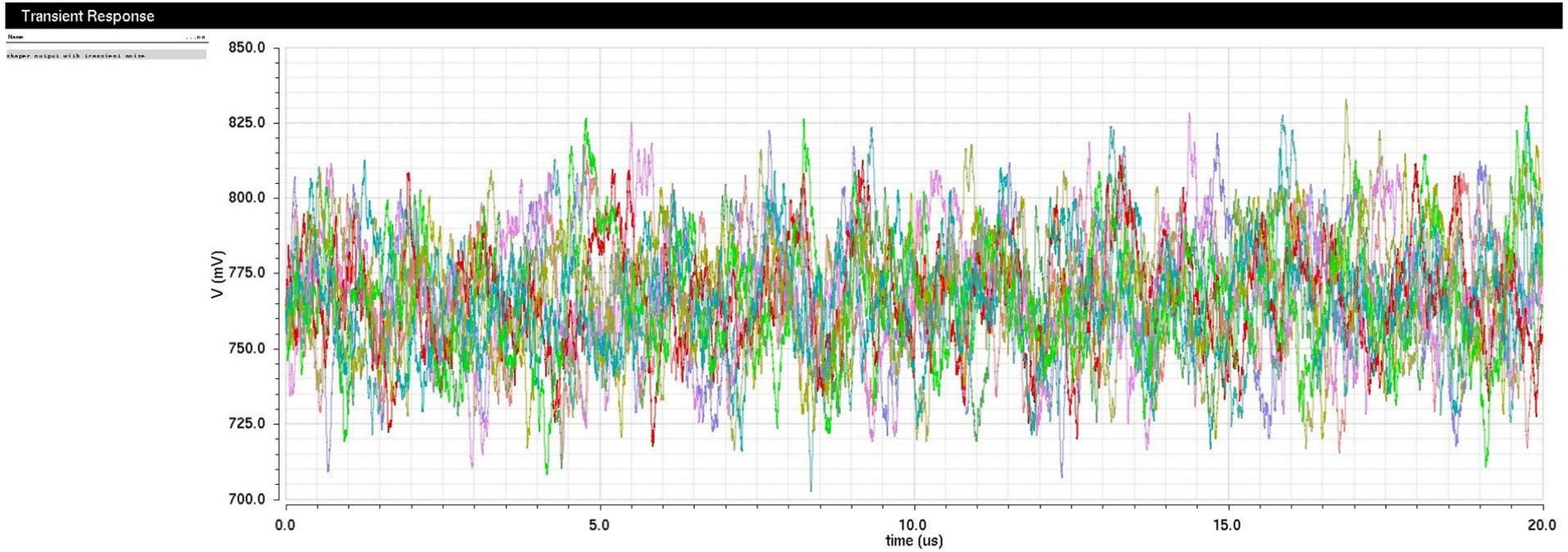


Charge injection

Pixel circuit ( $\sim 7.5 \mu A$ )

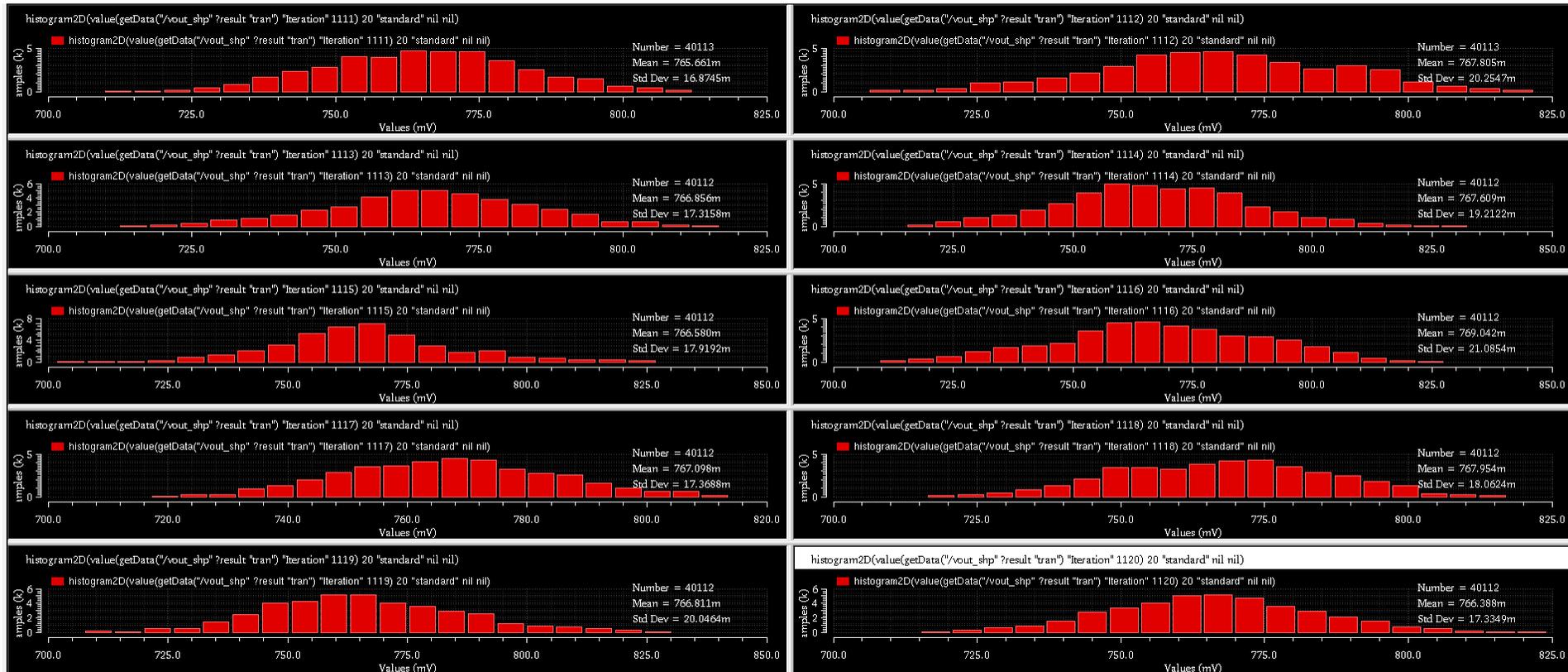


# Noise simulation



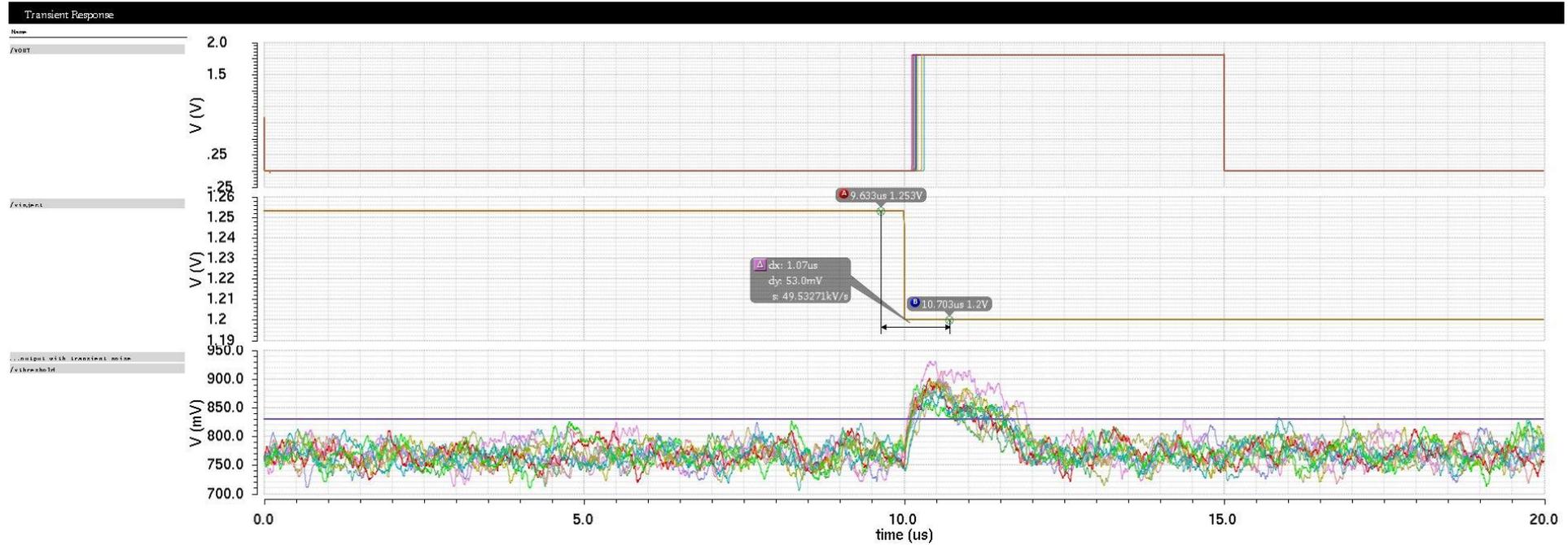
**Shaper output without charge**

# Noise simulation



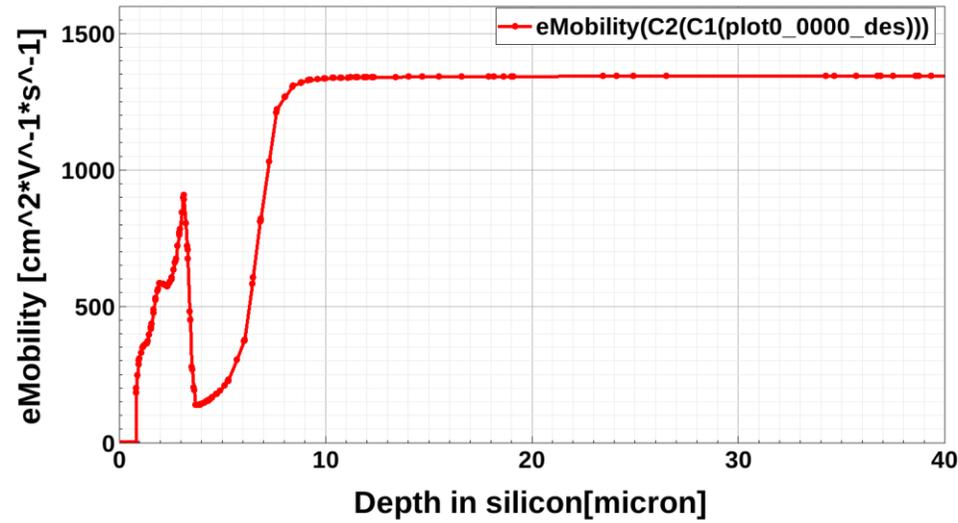
**Output histogram with transient noise**  
**Standard deviation ~ 18.5 mV**

# Noise simulation

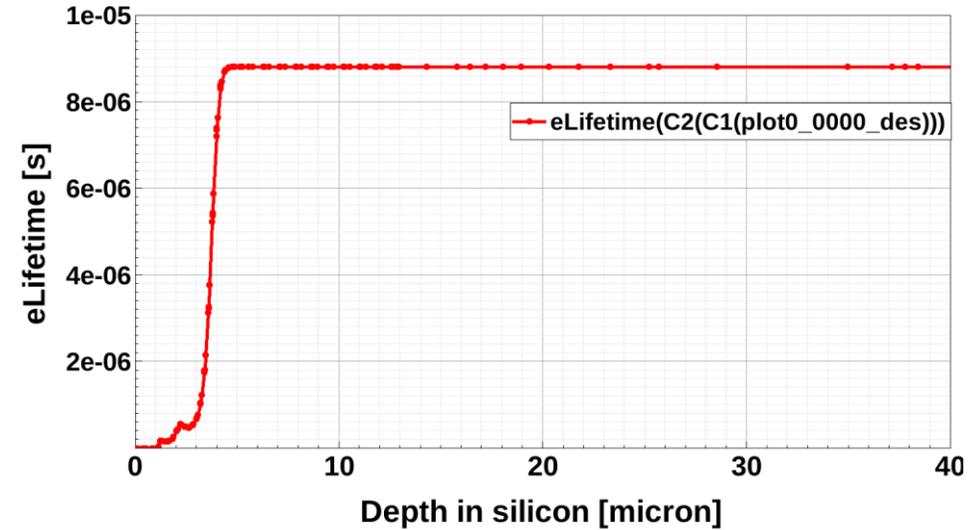


Simulation results with ~ 1000 e-

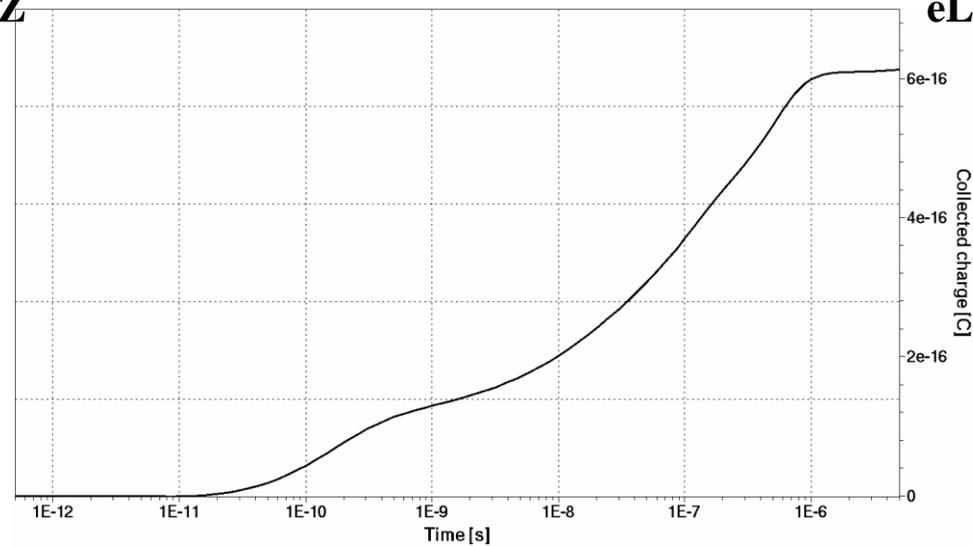
# Charge collection simulation



Depth in silicon[micron]  
eMobility vs. Z



Depth in silicon [micron]  
eLifetime vs. Z



Collected charge vs. time